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(54) **Title:** ABRASIVE TOOLS FOR GRINDING ELECTRONIC COMPONENTS

(57) **Abstract:** Abrasive tools containing high concentrations of hollow filler materials in a resin bond are suitable for polishing and backgrinding of hard materials, such as ceramic wafers and components requiring a controlled amount of surface defects. These highly porous abrasive tools comprise fine grit abrasive grain, such as diamond abrasive, along with the hollow filler material and resin bond, comprising a backing and an abrasive rim containing a maximum of about 2 to 15 volume percent abrasive grain, the abrasive grain having a maximum grit size of 60 microns, wherein the abrasive rim comprises resin bond and at least 40 volume percent hollow filler materials, and the abrasive grain and resin bond are present in the abrasive rim in a ratio of 1.5:1.0 to 0.3:1.0 grain to bond.